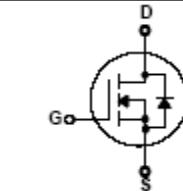


## HF2N60

### 600V N-Channel MOSFET

$BV_{DSS} = 600\text{ V}$   
 $R_{DS(on)\text{ typ}} = 4.0\text{ }\Omega$   
 $I_D = 2.0\text{ A}$



#### FEATURES

- Originative New Design
- Superior Avalanche Rugged Technology
- Robust Gate Oxide Technology
- Very Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Unrivalled Gate Charge : 9.0 nC (Typ.)
- Extended Safe Operating Area
- Lower  $R_{DS(ON)}$  : 4.0  $\Omega$  (Typ.) @  $V_{GS}=10\text{V}$
- 100% Avalanche Tested

#### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current – Continuous ( $T_C = 25^\circ\text{C}$ )	2.0*	A
	Drain Current – Continuous ( $T_C = 100^\circ\text{C}$ )	1.3*	A
$I_{DM}$	Drain Current – Pulsed (Note 1)	8.0*	A
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	150	mJ
$I_{AR}$	Avalanche Current (Note 1)	2.0	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	5.4	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	5.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	23	W
	– Derate above $25^\circ\text{C}$	0.18	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

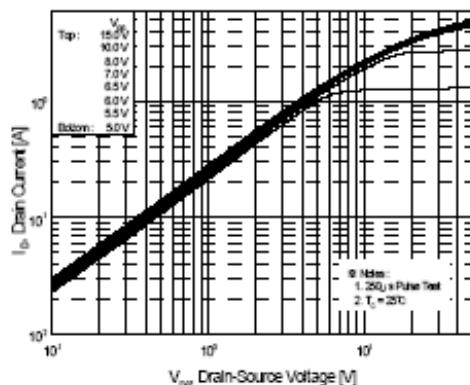
\* Drain current limited by maximum junction temperature

#### Thermal Resistance Characteristics

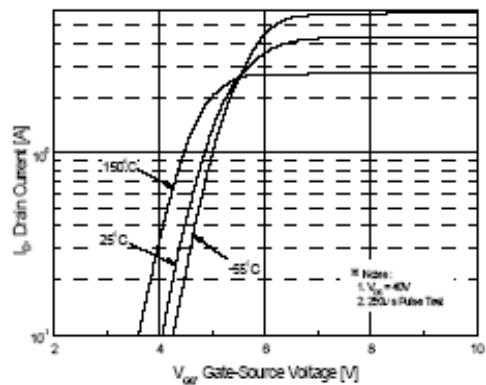
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	5.5	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	



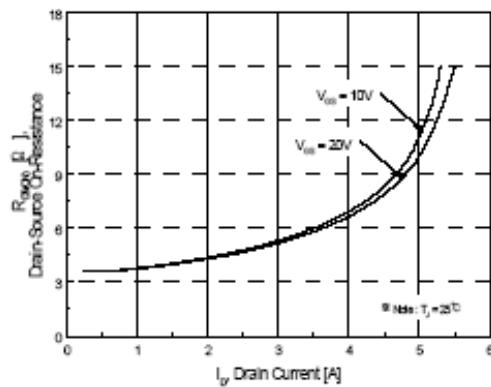
## Typical Characteristics



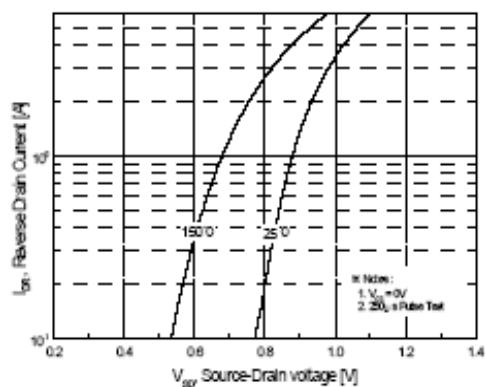
**Figure 1. On Region Characteristics**



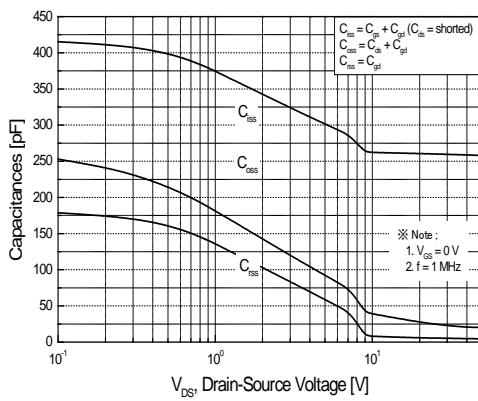
**Figure 2. Transfer Characteristics**



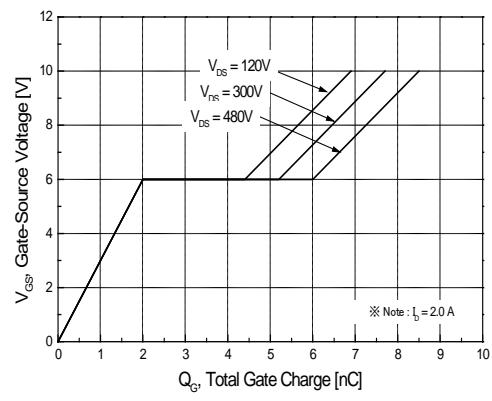
**Figure 3. On Resistance Variation vs Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**

## Typical Characteristics (continued)

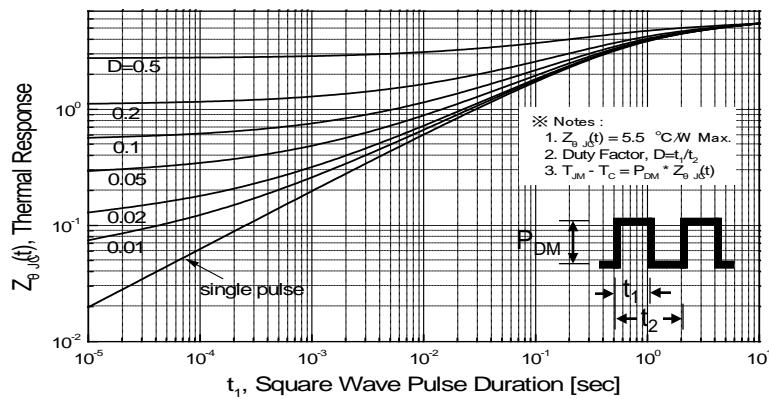
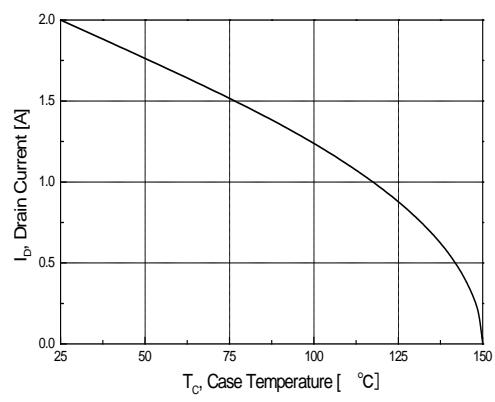
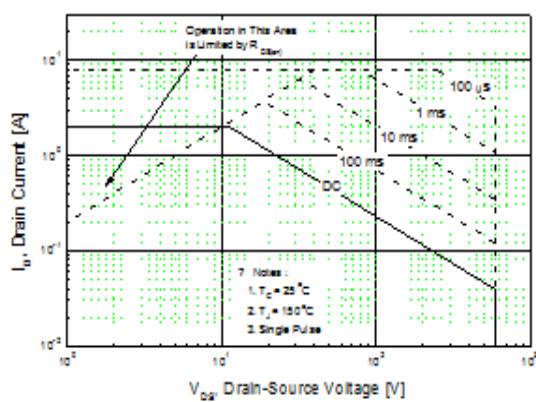
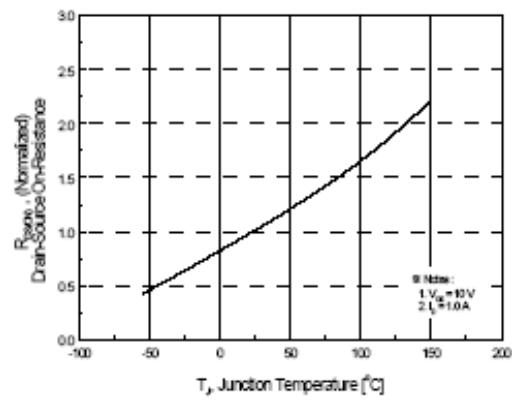
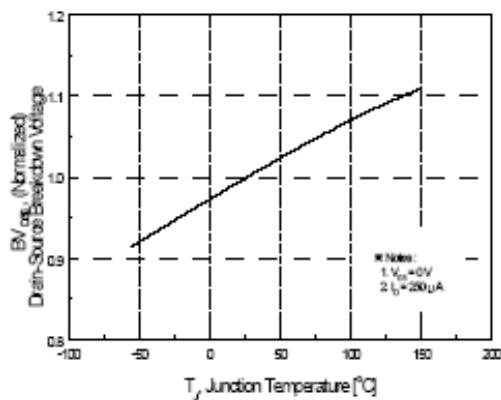


Fig 12. Gate Charge Test Circuit &amp; Waveform

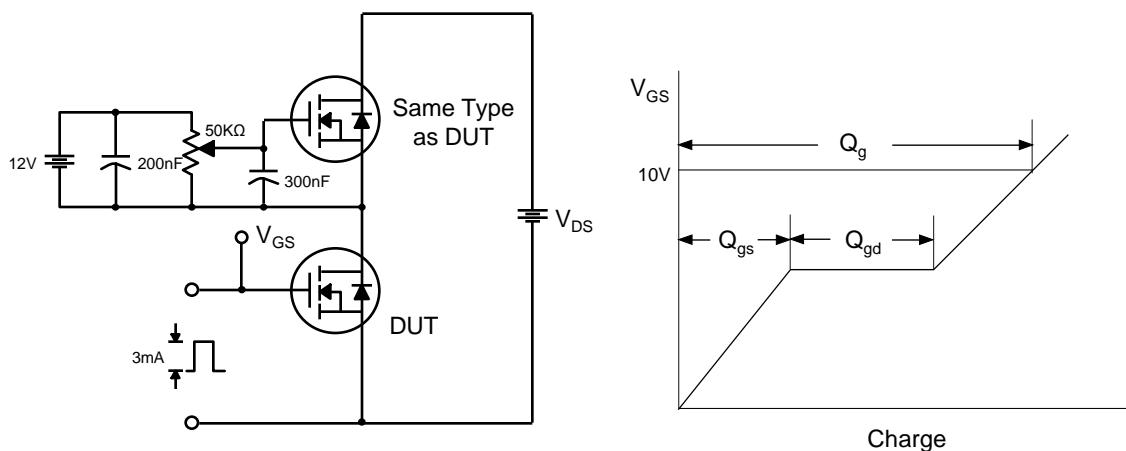


Fig 13. Resistive Switching Test Circuit &amp; Waveforms

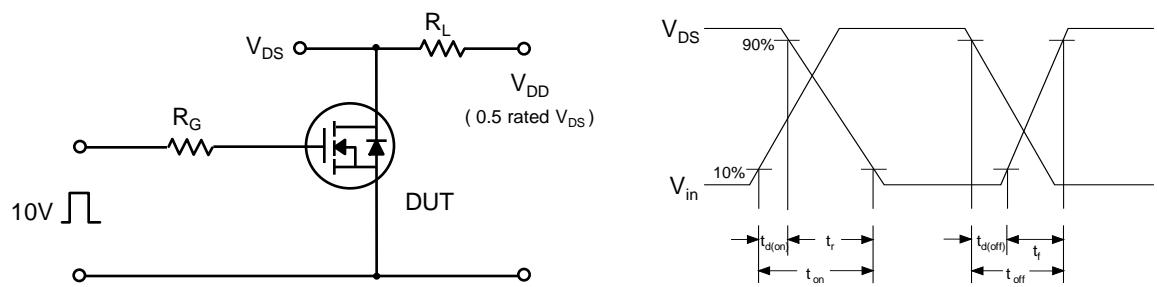


Fig 14. Unclamped Inductive Switching Test Circuit &amp; Waveforms

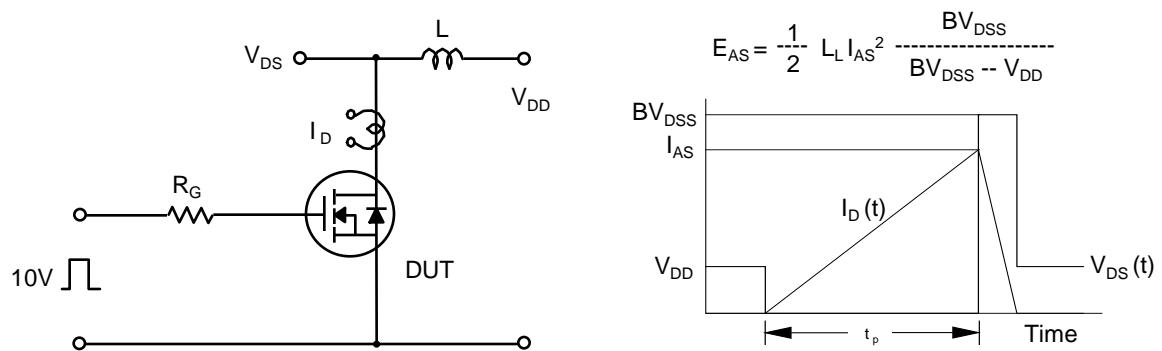
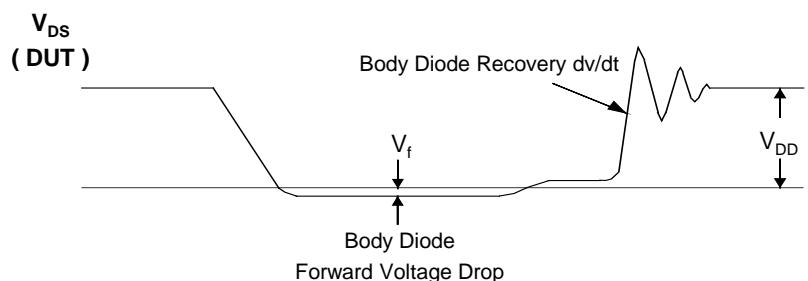
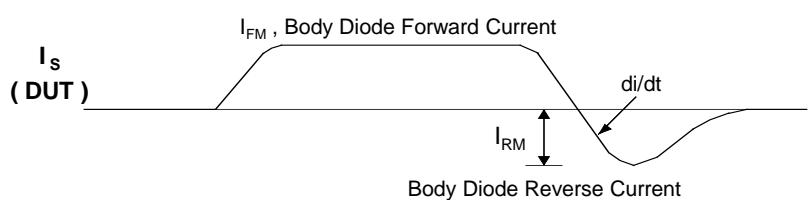
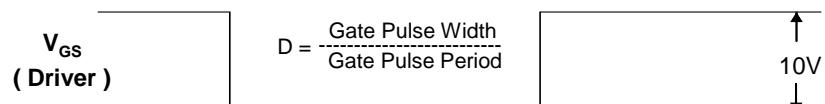
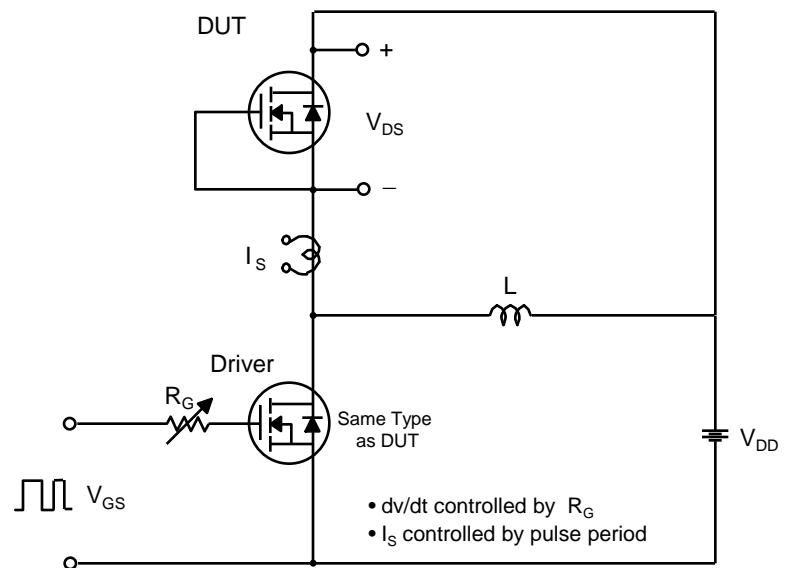


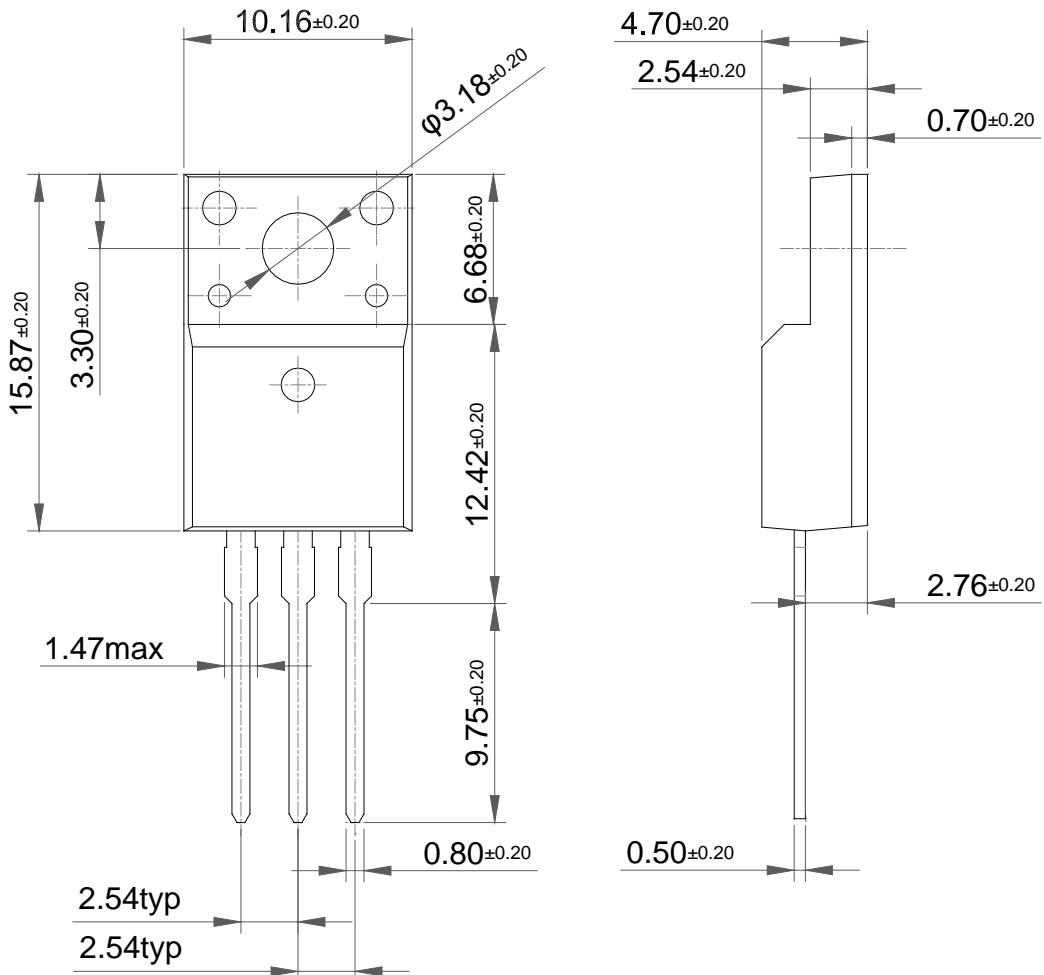
Fig 15. Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms



HF2N60

## Package Dimension

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